

High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, MQW

FEATURES

High reliability

· High radiant power

· Very high radiant intensity

Package type: surface mountPackage form: side view

Peak wavelength: λ_p = 940 nm

• Angle of half intensity: $\varphi = \pm 9^{\circ}$

· Suitable for high pulse current operation

please see www.vishay.com/doc?99912

Floor life: 168 h, MSL 3, according to J-STD-020

· Material categorization: for definitions of compliance

• Dimensions (L x W x H in mm): 3.2 x 2.51 x 1.2



DESCRIPTION

VSMB14940 is an infrared, 940 nm, side looking emitting diode in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted PCB based package (with lens) for surface mounting (SMD).

APPLICATIONS

- Emitter for remote control
- IR touch panels
- Photointerrupters
- Optical switch

PRODUCT SUMMARY COMPONENT Ie (mW/sr) φ (deg) λp (nm) tr (ns) VSMB14940 35 ± 9 940 15

Note

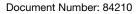
Test conditions see table "Basic Characteristics"

ORDERING INFORMATION							
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM				
VSMB14940	Tape and reel	MOQ: 1500 pcs, 1500 pcs/reel	Side view				

Note

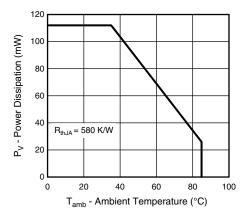
• MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)							
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT			
Reverse voltage		V _R	5	V			
Forward current		I _F	70	mA			
Surge forward current	t _p = 100 μs	I _{FSM}	500	mA			
Power dissipation		Pv	112	mW			
Junction temperature		Т _ј	100	°C			
Operating temperature range		T _{amb}	-40 to +85	°C			
Storage temperature range		T _{stg}	-40 to +100	°C			
Soldering temperature	According fig. 10, J-STD-020	T _{sd}	260	°C			
Thermal resistance junction / ambient	J-STD-051, soldered on PCB	R _{thJA}	580	K/W			



Pb-free (e3)





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Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

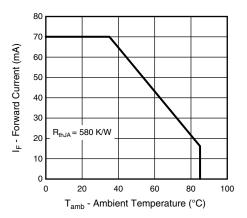


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)								
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT		
Forward voltage	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	V _F	1.05	1.24	1.5	V		
	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	V _F	-	1.33	1.6	V		
	I _F = 500 mA, t _p = 100 μs	V _F	-	1.8	-	V		
Temperature coefficient of V _F	I _F = 20 mA	TK _{VF}	-	-1.12	-	mV/K		
Reverse current	V _R = 5 V	I _R	-	-	10	μA		
Junction capacitance	$V_{R} = 0 V, f = 1 MHz, E = 0 mW/cm^{2}$	CJ	-	38	-	pF		
Radiant intensity	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	l _e	6.5	10.5	14.5	mW/sr		
	$I_F = 70 \text{ mA}, t_p = 20 \text{ ms}$	l _e	-	35	-	mW/sr		
	I _F = 500 mA, t _p = 100 μs	l _e	-	205	-	mW/sr		
Radiant power	I _F = 70 mA, t _p = 20 ms	фе	-	28	-	mW		
Temperature coefficient of radiant power	I _F = 20 mA	$TK\phi_{e}$	-	0.39	-	%/K		
Angle of half intensity		φ	-	± 9	-	deg		
Peak wavelength	I _F = 70 mA	λp	920	940	960	nm		
Spectral bandwidth	I _F = 30 mA	Δλ	-	30	-	nm		
Temperature coefficient of λ_p	I _F = 30 mA	ΤΚλρ	-	0.30	-	nm/K		
Rise time	I _F = 100 mA, 20 % to 80 %	t _r	-	15	-	ns		
Fall time	I _F = 100 mA, 20 % to 80 %	t _f	-	15	-	ns		

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

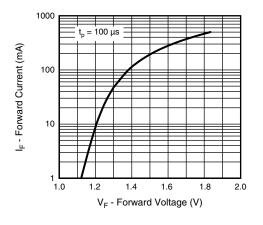


Fig. 3 - Forward Current vs. Forward Voltage

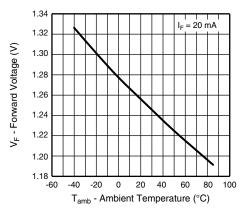


Fig. 4 - Forward Voltage vs. Ambient Temperature

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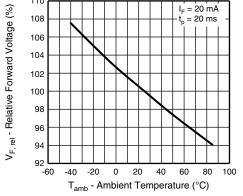


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

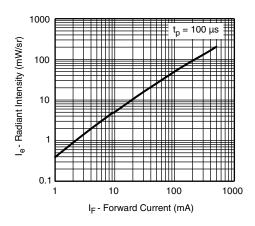


Fig. 6 - Radiant Intensity vs. Forward Current

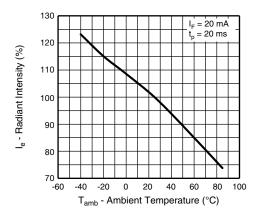


Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature

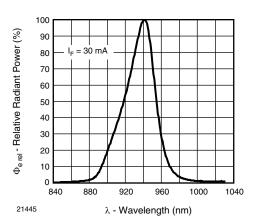


Fig. 8 - Relative Radiant Power vs. Wavelength

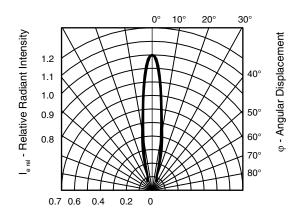
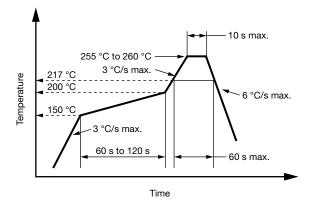


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE

SHA



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Fig. 10 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

PACKAGE DIMENSIONS in millimeters: VSMB14940

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

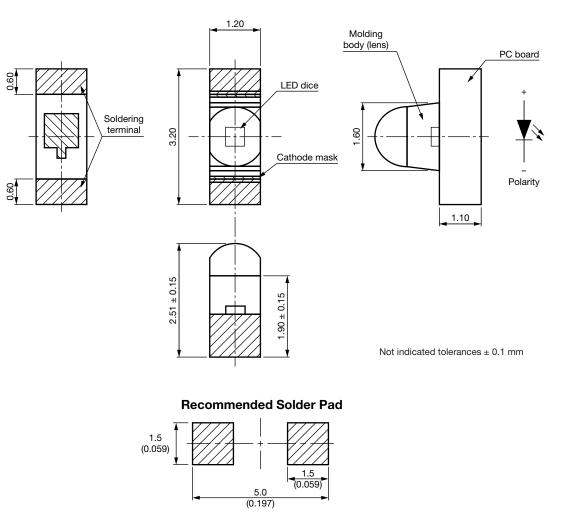
Floor life: 168 h

Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 3, according to J-STD-020.

DRYING

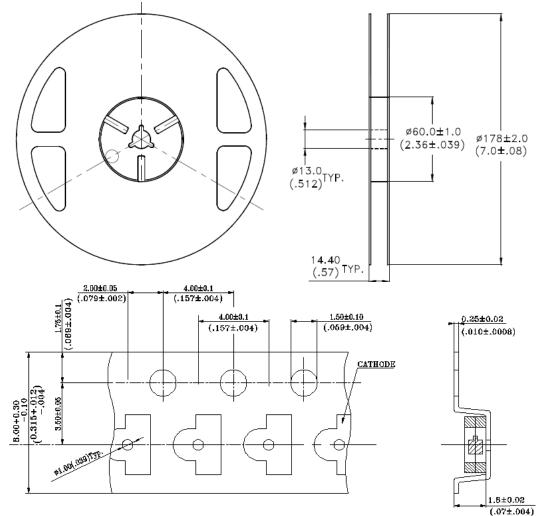
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.



4 For technical questions, contact: <u>emittertechsupport@vishay.com</u>



TAPING AND REEL DIMENSIONS in millimeters: VSMB14940





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